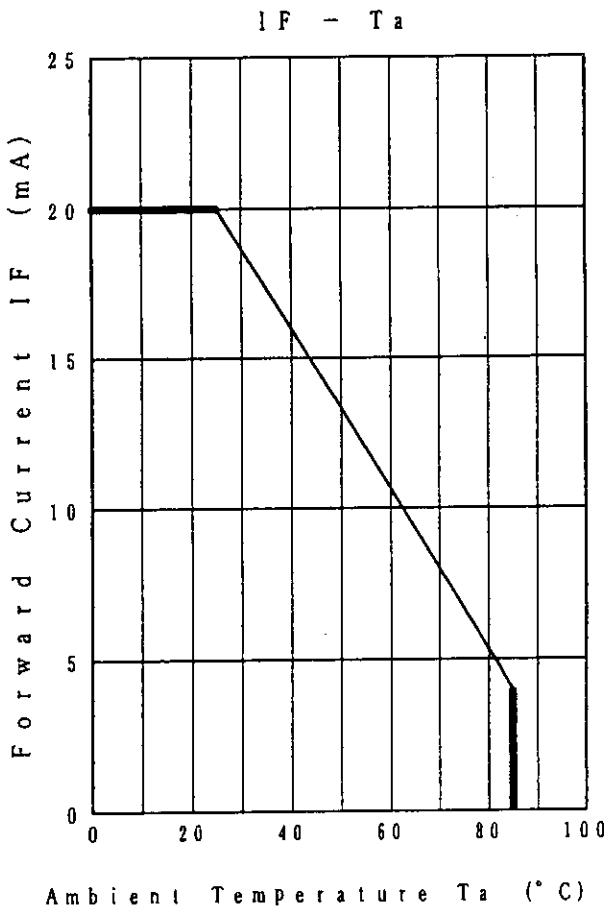
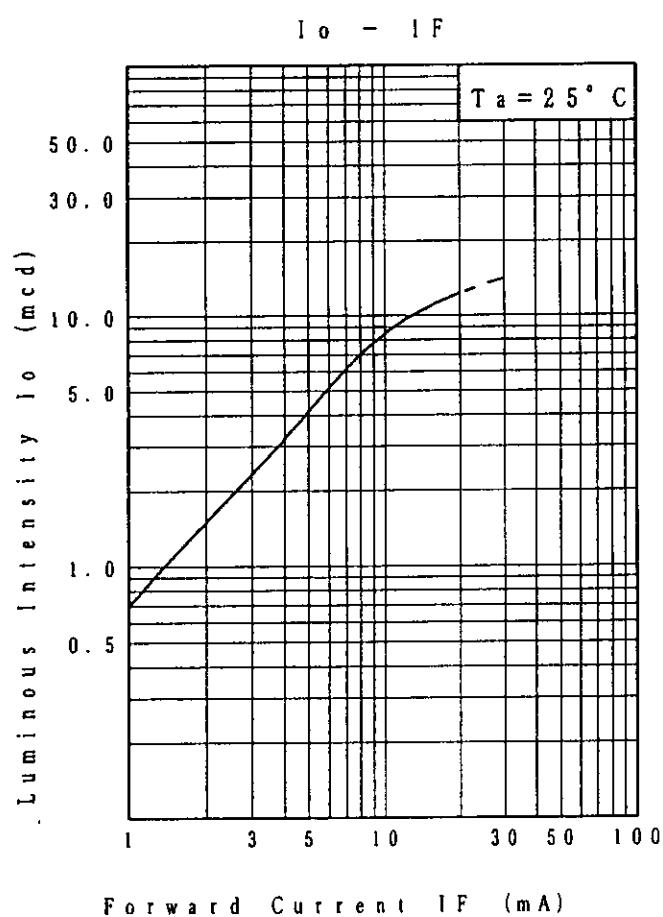
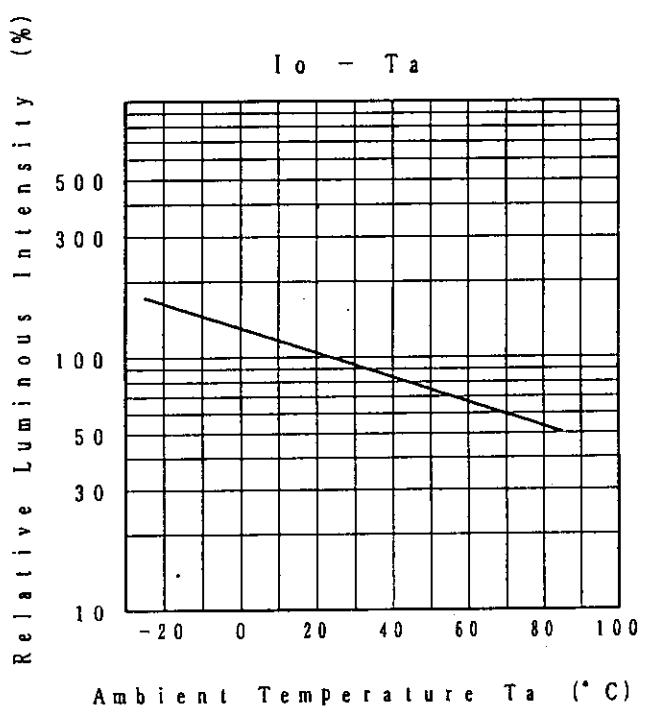
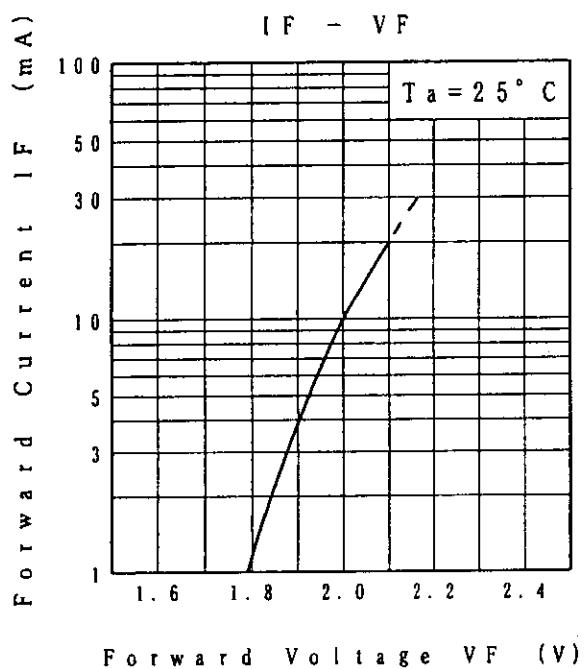


Approved	Checked	Designed	DEVELOPMENT SPECIFICATION						
<i>T. Yamada</i>	<i>T. Tabata</i>		P/N : LNJ406K54UX						
T Y P E	Amber Light Emitting Diode								
APPLICATION	Indicators								
MATERIAL	InGaAlP								
OUTLINE	Attached								
ABSOLUTE MAXIMUM RATINGS	P 50 mW	※IFP 60 mA	IFDC 20 mA	VR 4 V	Topr -25~+85 °C	Tstg -30~+100 °C			
CONDITION	Ta=25±3 °C								
Test Specification									
Item	Symbol	Condition	Typ	Limit		Unit			
				Min	Max				
Forward Voltage	VF	IF=10 mA	2.0		2.3	V			
Reverse Leakage Current	IR	VR= 4 V			100	μA			
Luminous Intensity	I <sub>O</sub>	IF=10 mA · DC	8.5	3.5		mcd			
Peak Emission Wavelength	λ <sub>p</sub>	IF=10 mA · DC	595			nm			
Spectral Line Half Width	Δλ	IF=10 mA · DC	15			nm			
<p>※ · The Condition of IFP is duty 10 %, Pulse width 1 ms  · Please contact the Panasonic local office if you design at low current  (below 1.0 mA DC) or pulse current operation and have any questions.</p>									
<b>NOTE</b> ★1 Soldering conditions. Refer to handling note.  ★2 Care should be taken that soldering is done within 3-days after opening the dry package and reel.  ★3 Package:Light yellow diffusion type.  ★4 A InGaAlP LED is sensitive to static electricity and care should be fully taken in handling it. Particularly, when an overvoltage is applied, which exceeds the absolute maximum rating of the InGaAlP LED, its energy damages the LED. Therefore, take utmost proactive measures against static electricity and surge as to building an assembly line and handling the LED halfway the process. (1) Check the entire drive circuit including the power source. For example, a surge current, etc., generated at power-on/off must not exceed the absolute maximum rating of the LED. Also, insert an appropriate protective circuit into the LED drive circuit. (2) Beware of destruction by static electricity in handling the LED. As proactive measures against static electricity, it is effective to earth your body(via 1MΩ), spread conductive mat on the floor, wear semiconductive work uniform and shoes, and use semiconductive containers. Also, be sure to earth the nose of a soldering iron. It is recommended to use an ionizer, etc., in the facility or environment where static electricity may be generated easily.									
Nov. 26. 1996									

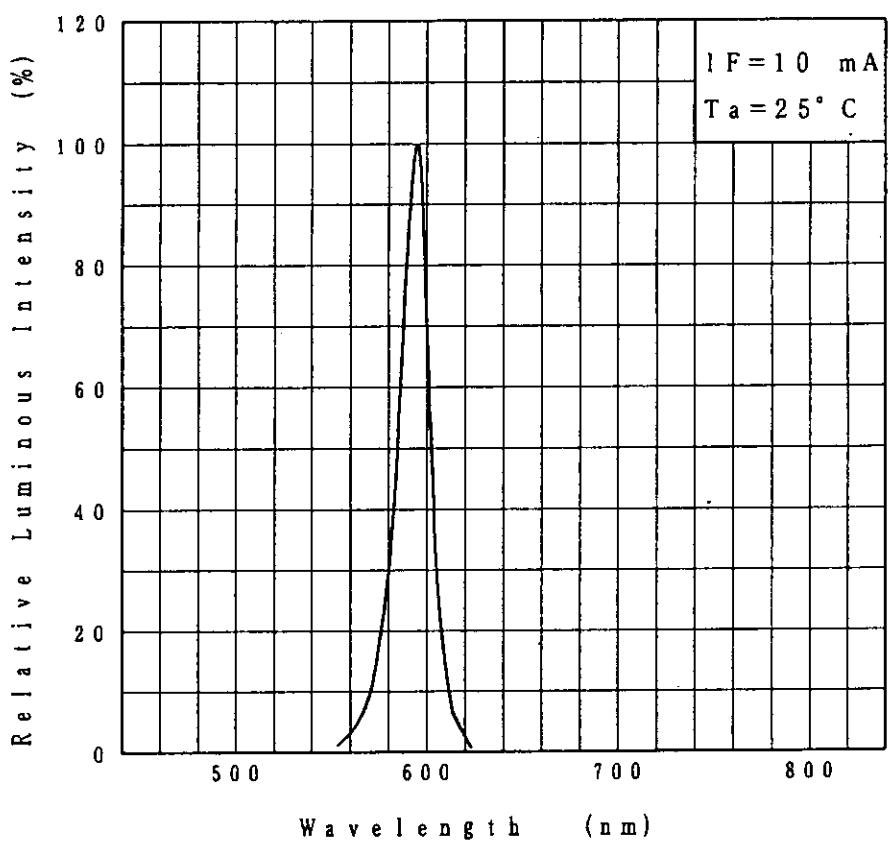
Approved	Checked	Designed	DEVELOPMENT SPECIFICATION				
<i>K.Yamada</i>	<i>T.Takida</i>	<i>T.Tabata</i>	P/N : LNJ406K54UX				



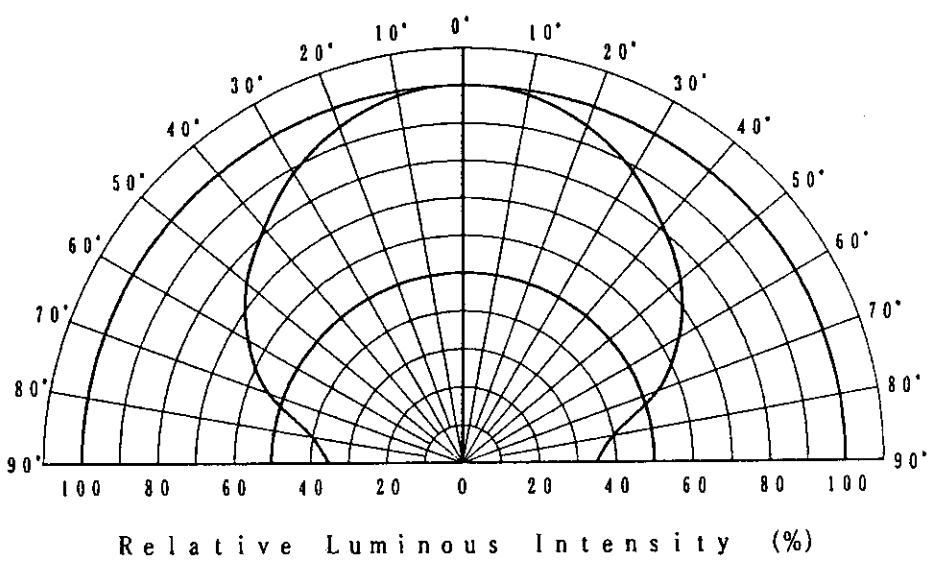
Nov. 27. 1996			
Panasonic	KAGOSHIMA MATSUSHITA ELECTRONICS CO., LTD.		KB-H-022-018B

Approved	Checked	Designed	DEVELOPMENT SPECIFICATION	
N.Y. Yamashita	T.Sekita	T.Tabata	P/N : LNJ406K54UX	

Relative Luminous Intensity  
Wavelength Characteristics



Directive Characteristics



Nov. 27. 1996

Panasonic

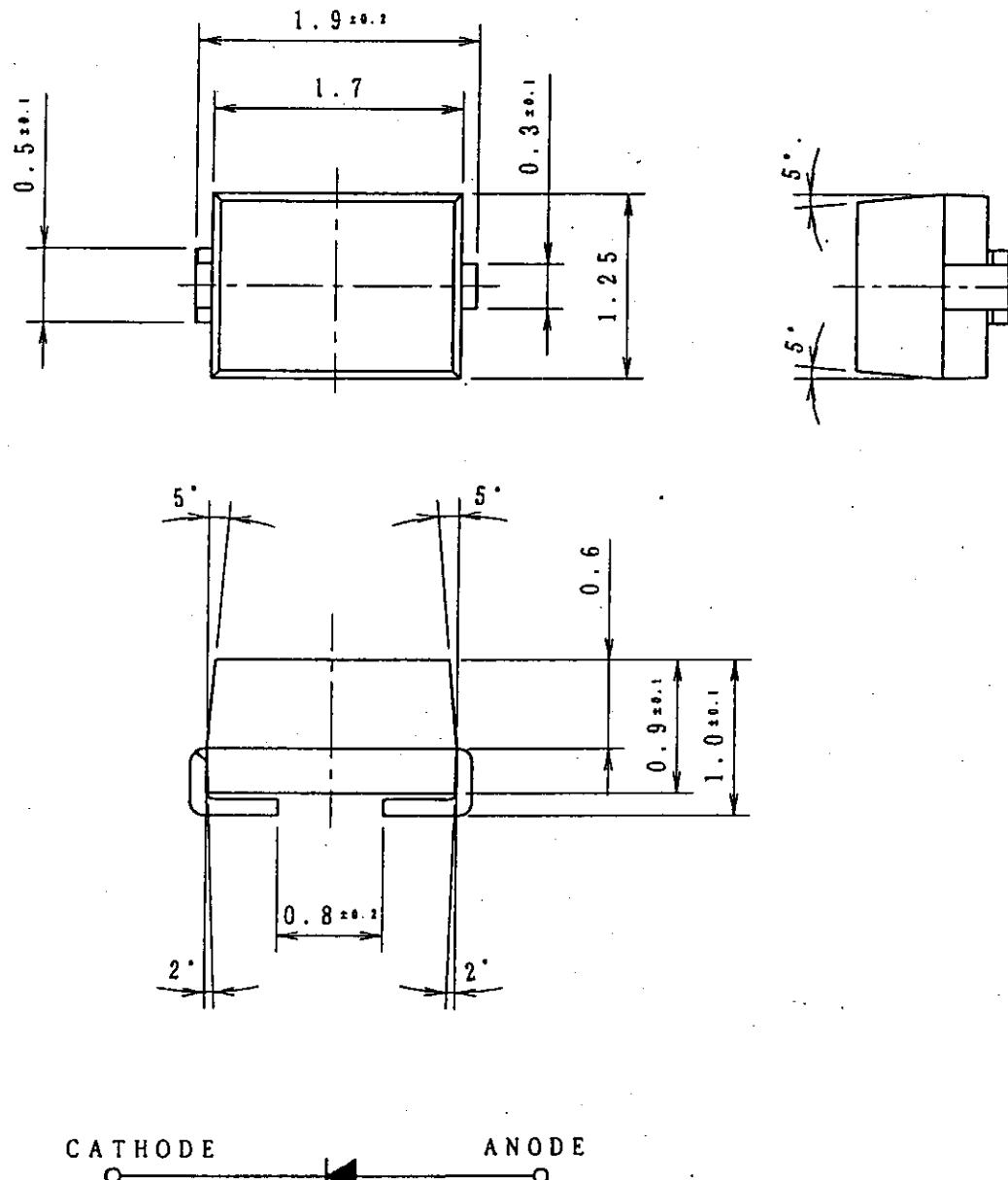
KAGOSHIMA MATSUSHITA ELECTRONICS CO., LTD.

KB-H-022-018B

Approved	Checked	Designed
N. Yaukishi	T. Iida	T. Tabata

DEVELOPMENT SPECIFICATION  
(OUTLINE)  
P/N:

P/N:



A diagram of a diode symbol. It consists of a vertical line with a small triangle pointing downwards at the top. A horizontal line extends from the left side of the vertical line to a small circle, labeled "CATHODE" above it. Another horizontal line extends from the right side of the vertical line to another small circle, labeled "ANODE" above it.

(NOTE)

1. Unit:mm
  2. Tolerance unless specified is  $\pm 0.2$ .
  3. Measurement of the package doesn't include gate projection.
  4. Corner of the package is R 0.2max.
  5. Projection's tolerance of the package is 0.2max.

Nov. 27. 1996

KAGOSHIMA MATSUSHITA ELECTRONICS CO., LTD.

$$K_B = 11 - 0.22 = 0.18 B$$